



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-05-11
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Flavio Di Francesco	Representative Title	AMS Material Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	IDK7*3079AE6	A	BO2A	2015-05-11
Amount	UoM	Unit type	ST ECOPACK Grade	
130.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
D50	8.6x3.9x1.52	14	gull wing	
Comment	Package: SO 14 .15 TO JEDEC MS-012; Md valid for MC33079YDT			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-17th December 2014				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	IDK7*3079AE6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies (choose)	Other inorganic materials	4.252	mg	supplier	die	Silicon (Si)	7440-21-3		4.177	mg	982361	32131
				supplier	metallization	Aluminium (Al)	7429-90-5		0.035	mg	8231	269
				supplier	Passivation	Silicon Nitride	12033-89-5		0.018	mg	4233	138
				supplier	Passivation	Silicon Oxide	7631-86-9		0.022	mg	5174	169
Leadframe	Copper & its alloys	48.397	mg	supplier	alloy	Copper (Cu)	7440-50-8		47.014	mg	971424	361646
				supplier	alloy	Iron (Fe)	7439-89-6		1.106	mg	22853	8508
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.067	mg	1384	515
				supplier	alloy	Zinc (Zn)	7440-66-6		0.058	mg	1198	446
				supplier	metallization	Nickel (Ni)	7440-02-0		0.139	mg	2872	1069
				supplier	metallization	Palladium (Pd)	7440-05-3		0.005	mg	103	38
				supplier	metallization	Gold (Au)	7440-57-5		0.004	mg	83	31
Die attach	Other inorganic materials	1.266	mg	supplier	metallization	Silver (Ag)	7440-22-4		0.004	mg	83	31
				supplier	glue or tape (choose)	Silver (Ag)	7440-22-4		1.152	mg	909953	8862
				supplier	glue or tape	acrylate	Proprietary		0.063	mg	49763	485
				supplier	glue or tape	Methacrylate	Proprietary		0.051	mg	40284	392
Bonding wire	Other inorganic materials	0.076		supplier	wire	Copper (Cu)	7440-50-8		0.076	mg	1000000	585
	Other inorganic materials	76.009	mg	supplier	mold compound	Epoxy Resin	Proprietary		5.701	mg	75004	43854
encapsulation	Other inorganic materials			supplier	mold compound	Phenol Resin	Proprietary		3.800	mg	49994	29231
				supplier	mold compound	Silica, vitreous	60676-86-0		65.824	mg	866003	506338
				supplier	mold compound	Carbon black	1333-86-4		0.380	mg	4999	2923
				supplier	mold compound	Bismuth (Bi)	7440-69-9		0.304	mg	4000	2338